



LM27403 Synchronous Buck Converter

TI reference design number: PMP8000

Input: 12V Output: 5V @ 30A

DC – DC Test Results



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1 Circuit Description

PMP8000 is a single-phase synchronous buck converter rated for 5V output at 30A from an input voltage of 12V. This design uses the LM27403 synchronous buck controller at a switching frequency of 500 kHz. CSD87350Q5D power block MOSFETs provide maximum efficiency when combined with a 250nH ferrite output inductor. The design solution uses all ceramic capacitors to fit into a minimum board area.

All tests were performed at room temperature on an open bench. A 470µF, 25V aluminum electrolytic input capacitor was used for input filter damping.

2 Photos

The photographs below show the PMP8000 Rev A assembly as built on PMP7935-A printed circuit board. This is a 4 layer board using 2 ounce copper on external layers and 1 ounce copper on internal layers. Power components are mounted on the top side of the board, with the control circuit on the bottom. The overall board dimensions are 2.5" x 2.5". The solution size component area is 1.1" x 0.65". The maximum component height is set by the inductor at 9.4 mm.



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3 Efficiency

The efficiency data is shown in the tables and graph below.



Vin(V)	lin(A)	Vout(V)	lout(A)	Efficiency(%)	Pin(W)	Pout(W)	Pdis(W)
12.000	0.135	5.017	0.00	0.000	1.62	0.00	1.62
12.000	0.510	5.018	0.90	73.794	6.12	4.52	1.60
12.000	1.350	5.020	2.90	89.864	16.20	14.56	1.64
12.000	2.195	5.021	4.92	93.786	26.34	24.70	1.64
12.000	3.045	5.024	6.94	95.420	36.54	34.87	1.67
12.000	3.905	5.026	8.94	95.887	46.86	44.93	1.93
12.0000	4.755	5.028	10.92	96.225	57.06	54.91	2.15
11.999	5.625	5.030	12.94	96.435	67.49	65.09	2.41
11.999	6.495	5.031	14.96	96.574	77.93	75.26	2.67
11.999	7.365	5.032	16.96	96.571	88.37	85.34	3.03
11.999	8.240	5.033	18.98	96.616	98.87	95.53	3.35
11.998	9.100	5.034	20.96	96.639	109.18	105.51	3.67
11.998	10.865	5.038	24.98	96.541	130.36	125.85	4.51
11.997	12.635	5.043	28.98	96.414	151.58	146.15	5.44
11.996	14.44	5.051	33.00	96.225	173.22	166.68	6.54
11.995	16.265	5.057	37.02	95.957	195.10	187.21	7.89
11.995	18.08	5.061	41.02	95.727	216.87	207.60	9.27
11.993	19.92	5.063	45.04	95.453	238.90	228.04	10.86



4 Thermal Tests

All tests were performed at room temperature on an open bench.

4.1 Test Setup

Thermal data was taken with a Fluke handheld thermal camera.





4.2 30A Load, No Airflow





5 Startup and Shutdown Behavior

5.1 Turn-on and Turn-off from Vin

The output voltage is well controlled at turn-on, showing no evidence of over-shoot.





5.2 Turn-on and Turn-off from EN

The output voltage is well controlled at turn-on, showing no evidence of over-shoot. Some ringing occurs at turn-off with load due to the output filter resonance.





6 Switching and Ripple

6.1 Switching and Ripple

Switching and ripple tests were made with a 470µF, 25V aluminum electrolytic input capacitor for input filter damping.





7 Load Transient Response

Load transient response for each condition was taken at two points to represent the minimum and maximum deviation. This difference occurs when the transient step coincides with either the converter off-time or on-time interval.

7.1 Load Transient Response

The output voltage transient is within 100mV for a 20A load step.



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